

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Patent Application of:	:	
Krishna G. Sachdev, <i>et al.</i>	:	
	:	
Conf. No.: 3517	:	Group Art Unit: 1712
	:	
Appln. No.: 10/709,518	:	Examiner: Michael J. Feely
	:	
Filing Date: May 11, 2004	:	Attorney Docket No.: FIS920030420US1
Title: THERMAL INTERFACE ADHESIVE AND REWORK		

AMENDMENT

The following Amendment is submitted in response to the non-final Office Action dated December 28, 2006 in the above-identified U.S. patent application. This amendment is being filed within the three-month statutory period set for a response. Please amend the above-identified U.S. patent application, without prejudice, as follows. No fee is believed to be due in connection with filing of this paper. However, if any such fee is due, please charge such fee to deposit account No. 09-0458.

Amendments to and Listing of the Claims begin on page 2 of this paper.

Remarks begin on page 9 of this paper.